

# TFT LCD Specification

**Customer:** \_\_\_\_\_  
**Model Name:** **ZE121BC-02A**  
**2ZE121BCA020S**  
**Date:** **2024/12/31**  
**Version:** **V0.5**

- Preliminary Specification  
 Final Specification

## For Customer's Acceptance

Approved by	Comment

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### RECORD OF REVISION

Version	Revise Date	Page	Description
0.1	2022/9/16	All	Preliminary spec for reference.
0.2	2023/2/9	5	Pin assignment modified for SEL68
		15	Modified the description of LVDS data input format of SEL68 setting
0.3	2023/4/6	4	Update NTSC value
		20	Add Polarizer axis degree information
		27	Add S/N Label coding rule
0.4	2024/6/24	-	Increase BL current Version
0.5	2024/12/31	5	Add definition of CONN1: Input LVDS CONN
		10	Fix ILED_VCCS on Current for Power
		11	FIX ILED1-~LED4- on Output Power Current
		19	Add Note(6) definition
		25	Fix Notes definition on FOG Drawing

## 1. FEATURES

ZE121BC-02A is a transmissive type color active matrix liquid crystal display (LCD), which uses amorphous thin film transistor (TFT) as switching devices. This panel has a 12.1 inches diagonally measured active display area with resolution 1024 x 768. This product is composed of a TFT LCD panel, polarizers, driver ICs, FPC and PCBA.

Note: Air-Bonding is recommended.

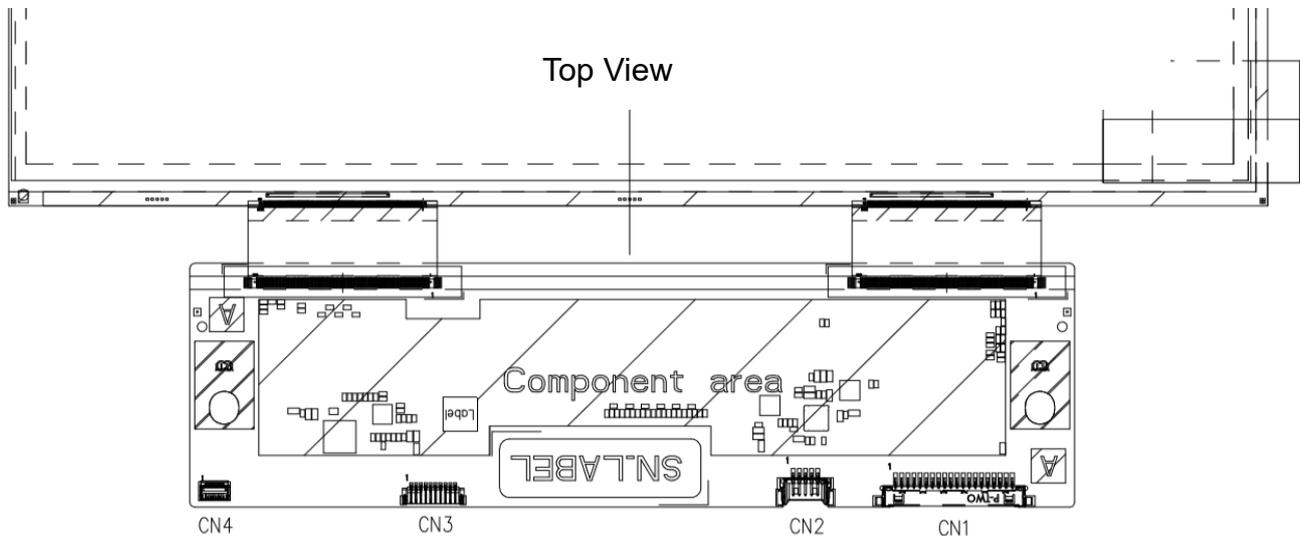
## 2. GENERAL SPECIFICATIONS

Item	Description	Unit
Display Size	12.1	inch
Display Type	Transmissive, a-Si	-
Active Area (HxV)	245.76 (H) x 184.32 (V)	mm
Number of Dots (HxV)	1024 x RGB x 768	dot
Pixel Pitch(HxV)	0.08 x 0.08	mm
Color Arrangement	RGB Stripe	-
Color Numbers	256K(6bits)/16.7 M(6+2 bits)	-
Outline Dimension (HxVxD)	256.18 (H) x 196.9 (V) x 1.27 (D)	mm
NTSC (CIE1931) (Under C light)	70 (Typ.)	%
White Point (x,y) (Under C light)	x:0.305,y: 0.347(Typ.)	
Response Time	≤35	ms
Viewing Angle (Light On) (R/U/L/D)	CR ≥ 10 @ R/L/U/D(85°/85°/85°/85°) (Min.)	
Surface Treatment	AG	
Contrast Ratio (Light On)	1000:1 (Typ)	
Operation Temperature	-30~85	□
Storage Temperature	-30~85	□
Interface	LVDS	
Weight	157.2 (Typ)	g
Panel power consumption	Max:(1.353W )@white pattern	W

### 3. PIN DESCRIPTION

#### 3.1 Connector

There are 4 connectors on PCBA, location & Pin1 is showed on below figure.



Connectors' type:

1. CN1 : Input LVDS CONN,20pins, P-TWO 187191-20101-3
2. CN2: OTP VCOM CONN,5pins, CI4205M2HRD-NH or ACES 50277-00501-002
3. CN3: Input BL power CONN,10pins, ACES, 91208-01001-H01
4. CN4:Output BL power CONN, 8pins, P-two: 196243-08041-3

#### 3.2 PIN assignment

##### 3.2.1 Connector 1 : Input LVDS CONN

A 20pin connector of P-two 187191-20101-3 is used for the module electronics interface. And a special plug needed for connecting this connector, the recommended model is JAE FI-S20S.

Pin assignment:

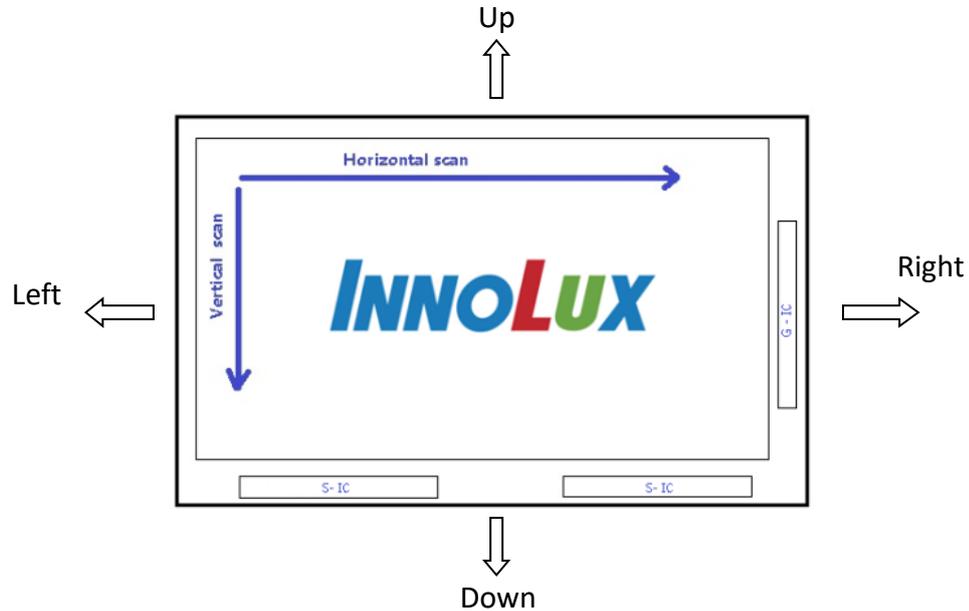
Pin NO.	Symbol	Description	Note
1	RX3+	Differential Data Input, CH3 ( Positive )	
2	RX3-	Differential Data Input, CH3 ( Negative )	
3	BIST	Normal operation/BIST pattern select BIST=0: Normal operation BIST=1: BIST mode	1
4	SEL68	LVDS 6/8 bit select function control, SEL68=1: LVDS input data is 8 bit SEL68=0: LVDS input data is 6 bit	2
5	GND	Ground	

6	RXC+	Differential Clock Input ( Positive )	
7	RXC-	Differential Clock Input ( Negative )	
8	GND	Ground	
9	RX2+	Differential Data Input, CH2 ( Positive )	
10	RX2-	Differential Data Input, CH2 (Negative )	
11	GND	Ground	
12	RX1+	Differential Data Input, CH1 ( Positive )	
13	RX1-	Differential Data Input, CH1 (Negative )	
14	GND	Ground	
15	RX0+	Differential Data Input, CH0 ( Positive )	
16	RX0-	Differential Data Input, CH0 (Negative )	
17	reLR	Left or right display control LR=1: Left-->Right LR=0: Right--> Left	3
18	reUD	Up or Down display control LR=1: Up-->Down LR=0: Down--> Up	3
19	VDD	Power supply. 3.3V	
20	VDD	Power supply. 3.3V	

Note:

1. Pin1 is reversed as BIST function for test, don't connect signal to this pin, keep floating.
2. SEL68 is used for selecting 6bit/8bit LVDS data input, 1: connect to VDD -->8bit; 0: connect to GND-->6bit.
3. reLR & reUD are used for selecting scanning direction.0: connect to GND; 1: connect to VDD.

Setting of scan control input		Scanning direction
reLR	reUD	
1	1	left to right ,up to down
1	0	left to right, down to up
0	1	right to left ,up to down
0	0	right to left ,down to up



### 3.2.2 Connector 2: OTP VCOM CONN

CONN type: CI4205M2HRD-NH or ACES 50277-00501-002, the recommended male connector is ACES 50280-005H0H0-001 or equivalent.

5-pin connector is used for OTP VCOM

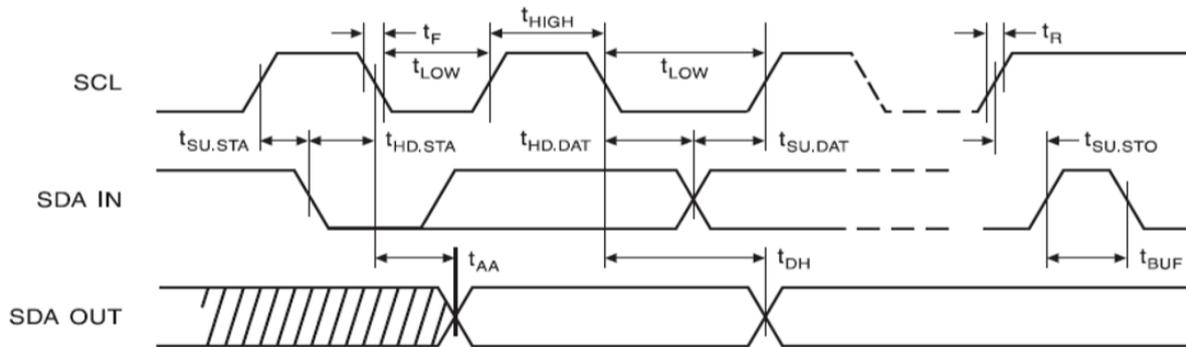
Pin NO.	Symbol	Description	Note
1	SCL	2-Wire I2C Clock Input.	1,2
2	SDA	2-Wire I2C Data Input.	1,2
3	WP	Write Protection Pin. WPN=0: disable write to EEPROM; WPN=1: enable write to EEPROM	
4	GND	ground	
5	GND	ground	

Note1: I2C DC/AC CHARACTERISTICS as following.

Parameter	Symbol	Value	Min.	Typ.	Max.	Unit
Low Level Input Voltage	$V_{IL}$	VIN=2.5V to 5.5V	0		0.8	V
High Level Input Voltage	$V_{IH}$	VIN=2.5V to 5.5V	1.5		5.5	V
SDA, SCL Hysteresis			0.6	0.7	0.8	V
Internal Pull High Resistor	$R_{PULL-1}$	A0 internal pull high(VIN1) resistor	8	10	12	K $\Omega$
EEPROM Write Protect		When WPN = High, can't write EEPROM	1.5		5.5	V
EEPROM Write Time	$T_{WRITE}$		30		500	msec
Number of Guaranteed EEPROM Write Cycles	$N_{WRITE}$		1		1000	Cycles

Symbol	Description	Min.	Typ.	Max.	Unit
$F_{SCL}$	Clock Frequency, SCL	0	-	400	kHz
$t_{LOW}$	Clock Pulse Width Low	1.3	-		us
$t_{HIGH}$	Clock Pulse Width High	0.6	-		us
$t_1$	Noise Suppression Time(2)			10	ns
$t_{BUF}$	Time the bus must be free before a new transmission can start(2)	1.3			us
$t_{HD,STA}$	Start Hold Time	0.6			us
$t_{SU,STA}$	Start Setup Time	0.6			us
$t_{HD,DAT}$	Data In Hold Time	0		900	ns
$t_{SU,DAT}$	Data In Setup Time	100			ns
$t_R$	Inputs Rise Time(2)			1	us
$t_F$	Inputs Fall Time(2)			300	ns
$t_{SU,STO}$	Stop Setup Time	0.6			us
$t_{AA}$	Clock Low to Data Out Valid	0.1		0.9	us
$t_{DH}$	Data Out Hold Time	50			ns

### I2C Bus Timing



Note 2: OTP D-VCOM adjust flow as Appendix 1

### 3.2.3 Connector 3: Input BL power CONN

CONN type: ACES, 91208-01001-H01 the recommended male connector is ACES:50216-01011-001 or equivalent.

10-pin connector pin assignment:

Pin NO.	Symbol	Description
1	LED_VCCS	LED convertor input power, 12V
2	LED_VCCS	LED convertor input power, 12V
3	LED_VCCS	LED convertor input power, 12V
4	LED_VCCS	LED convertor input power, 12V
5	GND	Ground
6	GND	Ground
7	GND	Ground

8	GND	Ground
9	LED_EN	Converter power IC output Enable (Active High)
10	LED_PWM	PWM control signal for LED convertor

### 3.2.4 Connector 4: Output BL power CONN

CONN type: P-two: 196243-08041-3, Applicable FPC/FFC : 0.5mm pitch/8-pin, refer to Appendix 2 for detail dimension.

8-pin connector pin assignment:

Pin NO.	Symbol	Description	Note
1	VLED+	Anode for light bar	
2	VLED+	Anode for light bar	
3	NC	No Connection	
4	NC	No Connection	
5	LED4-	Cathode for light bar	
6	LED3-	Cathode for light bar	
7	LED2-	Cathode for light bar	
8	LED1-	Cathode for light bar	

## 4. ABSOLUTE MAXIMUM RATING

Item	Symbol	Min.	Max.	Unit	Remark
Power Supply Voltage	VDD	-0.3	4.0	V	
	LED_VCCS	-0.3	25	V	
Storage Temperature	Tstg	-30	+85	°C	
Operating Temperature	Topr	-30	+85	°C	

Note:

- (1) All of the voltages listed above are with respective to GND= 0V
- (2) Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above.

## 5. DC CHARACTERISTICS

### 5.1 Parameter

Item	Symbol	Values			Unit	Remark
		Min.	Typ.	Max.		
Power voltage	VDD	3.0	3.3	3.6	V	
	LED_VCCS	11	12	13	V	
Input logic high voltage	V <sub>IH</sub>	0.7VDD	-	VDD	V	Note 1
Input logic low voltage	V <sub>IL</sub>	0	-	0.3VDD	V	
Current for Power	I <sub>VDD</sub>		-	410	mA	VDD =3.3V@frame 60 Hz, White pattern
	I <sub>LED_VCCS</sub>	455	-	505	mA	LED_VCCS=12V, PWM Duty =100%, @ (8S4P)
		693		732	mA	LED_VCCS=12V, PWM Duty =100%, @ (11S4P)
Inrush Current of Input Power	I <sub>VDD_inrush</sub>	-	-	1	A	VDD raise up time 0.5ms
	I <sub>LED_VCCS_inrush</sub>	-	-	1.5	A	LED_VCCS raise up time 0.5ms
LED_EN Control Level		3.0	-	5	V	
	BL Off	0	-	0.3	V	
LED_PWM Control Level	PWM High Level	3.0	-	5	V	
	PWM Low Level	0	-	0.3	V	
LED_PWM Control Frequency	f <sub>PWM</sub>	1K	-	20K	Hz	Note 2

Note 1: Including signal: BIST,SEL68 & reLR & reUD

Note 2: LED\_PWM duty >10%.

## 5.2 LB power output

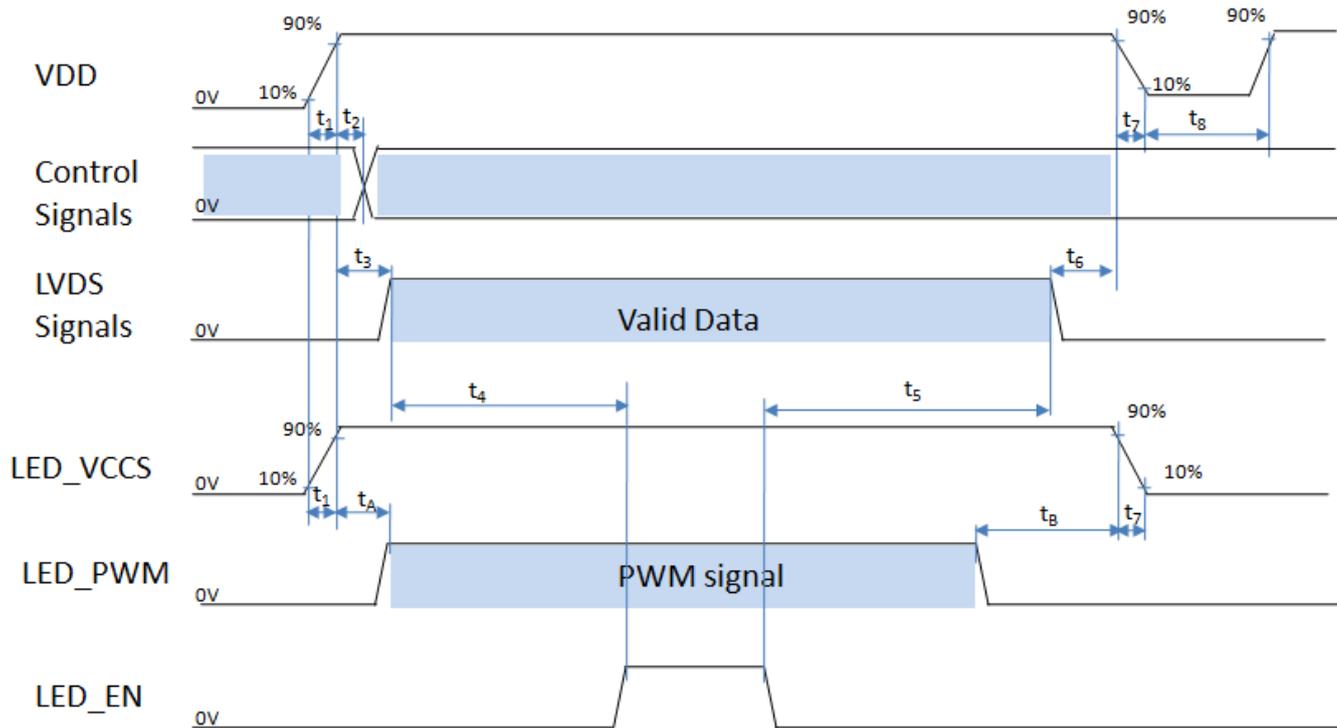
Item	Symbol	Values			Unit	Remark
		Min.	Typ.	Max.		
Output Power Voltage	LED+	23	24	25	V	LED+ =24V @8S4P
		35	36	37		LED+ =36V @11S4P
Output Power Current	I <sub>LED1~LED4</sub>	49.5	50	50.5	mA	Total 200mA(Typ.)(50mA x 4channel)

Note 1: output power LED+ OVP is 40V.

## 5.3 Power sequence

The power sequence specifications are shown as the following table and diagram.

Symbol	Value		Unit
	Min.	Max.	
t <sub>1</sub>	1	20	ms
t <sub>2</sub>	1	5	ms
t <sub>3</sub>	10	50	ms
t <sub>4</sub>	200	500	ms
t <sub>5</sub>	200	500	ms
t <sub>6</sub>	50	200	ms
t <sub>7</sub>	0	20	ms
t <sub>8</sub>	500	-	ms
t <sub>A</sub>	0	50	ms
t <sub>B</sub>	0	50	ms



Note 1: Please don't plug the interface cable of on when system is turned on.

Note 2: Please avoid floating state of the interface signal during signal invalid period.

Note 3: It is recommended that the backlight power must be turned on after the power supply for LCD and the interface signal is valid.

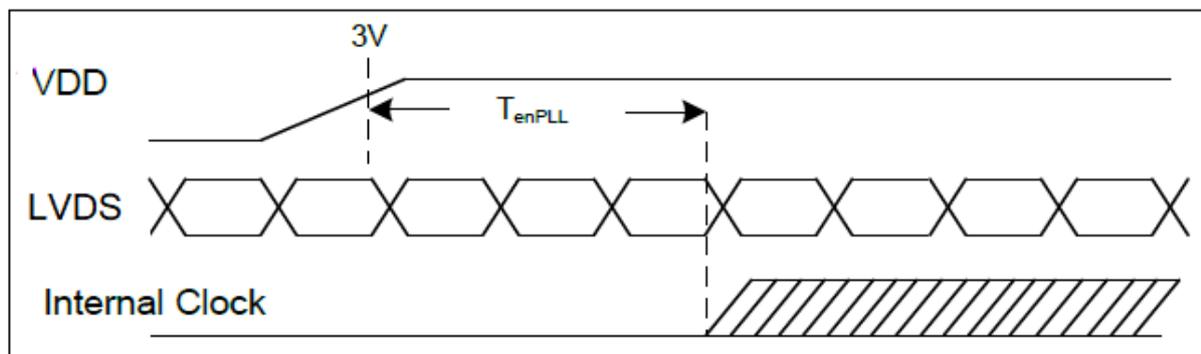
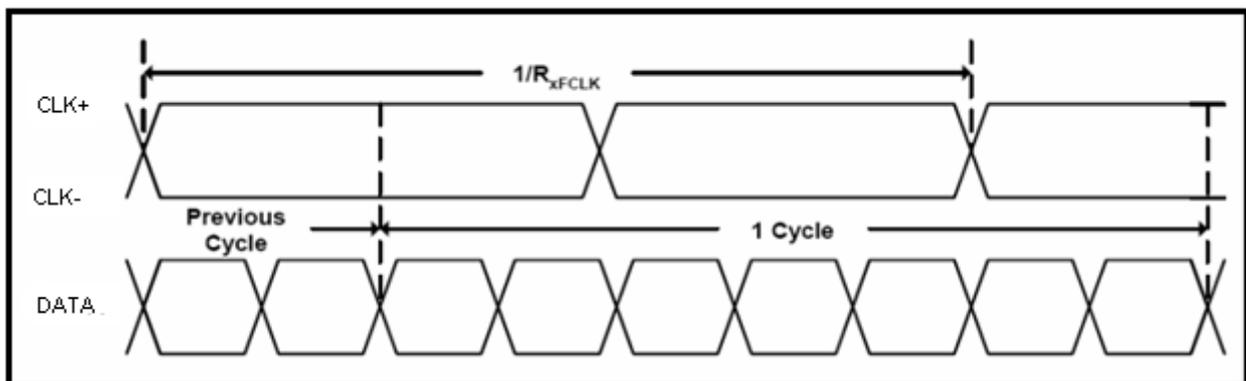
Note 4: Control signals include BIST, SEL68 , reUD & reLR.

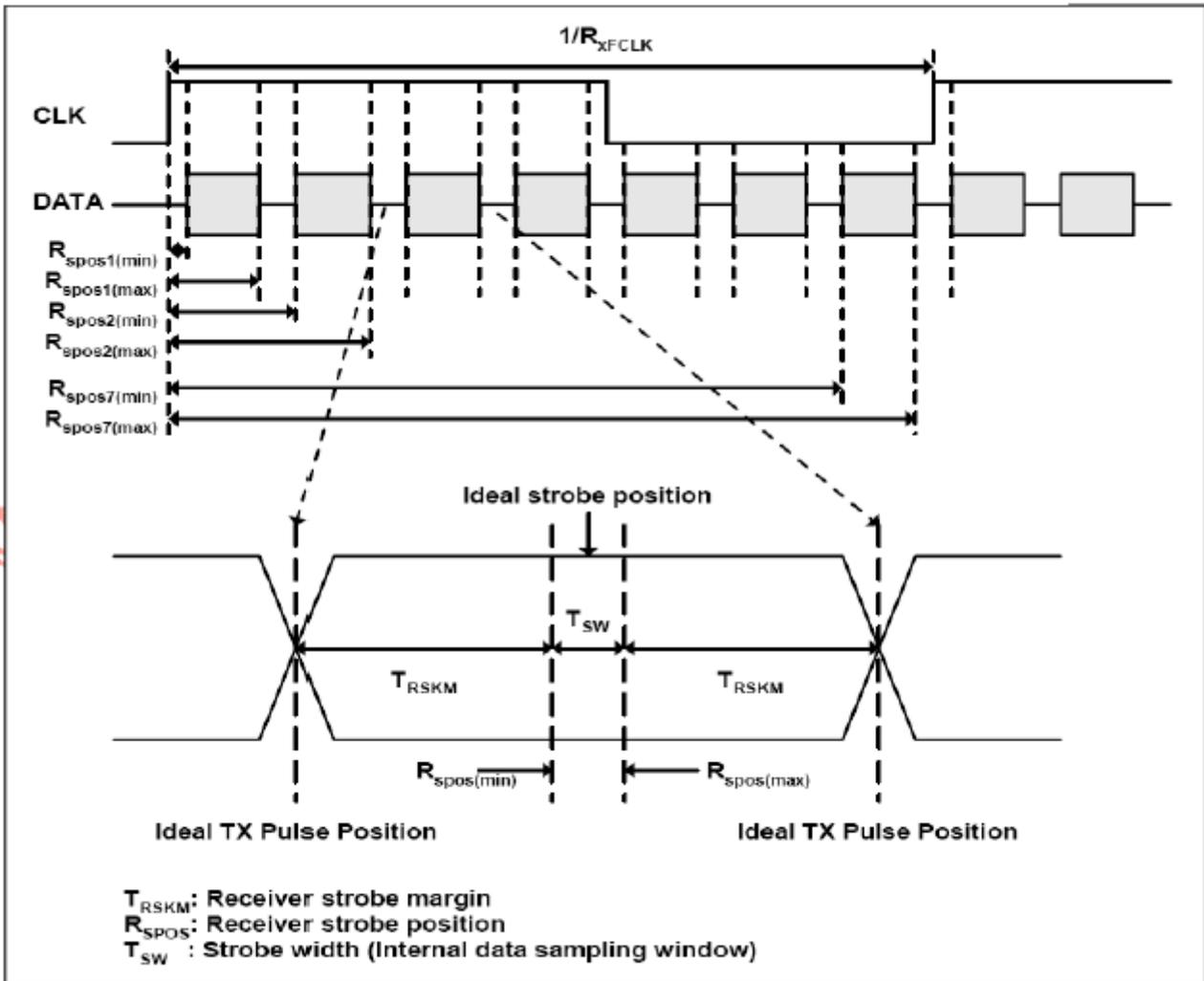
## 6. LVDS SIGNAL TIMING CHARACTERISTICS

### 6.1AC Electrical characteristics

Parameter	Symbol	Min	Typ	Max	Units	Condition
Clock frequency	RxFCLK	26.2	-	71	MHz	
Input data skew margin	TRSKM	500	-	-	ps	VID   = 400mV RxVCM=1.2V RxFCLK=71MHz
Clock high time	TLVCH	-	$4/(7 \times RxFCLK)$	-	ns	
Clock low time	TLVCL	-	$3/(7 \times RxFCLK)$	-	ns	
PLL wake-up time	TenPLL	-	-	150	us	

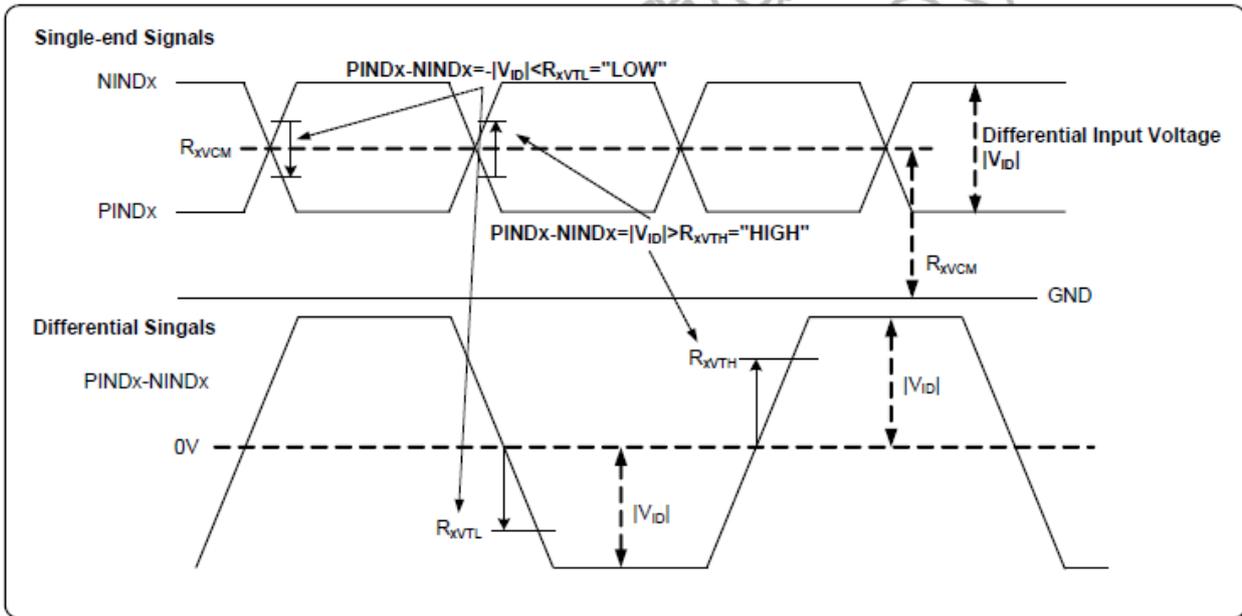
### 6.2 Input clock and data timing diagram





### 6.3 DC electrical characteristics

Parameter	Symbol	Values			Unit	Remark
		Min.	Typ.	Max.		
LVDS Differential input high Threshold voltage	$R_{XVTH}$	-	-	+100	mV	$R_{XVCM}=1.2V$
LVDS Differential input low Threshold voltage	$R_{XVTL}$	-100	-	-	mV	
Input Voltage range (Singled-end)	$R_{XVIN}$	0	-	2.4	V	
LVDS Differential input common mode voltage	$R_{XVCM}$	$ V_{ID} /2$	-	$2.4- V_{ID} /2$	V	
LVDS Differential input voltage	$ V_{ID} $	0.2	-	0.6	V	

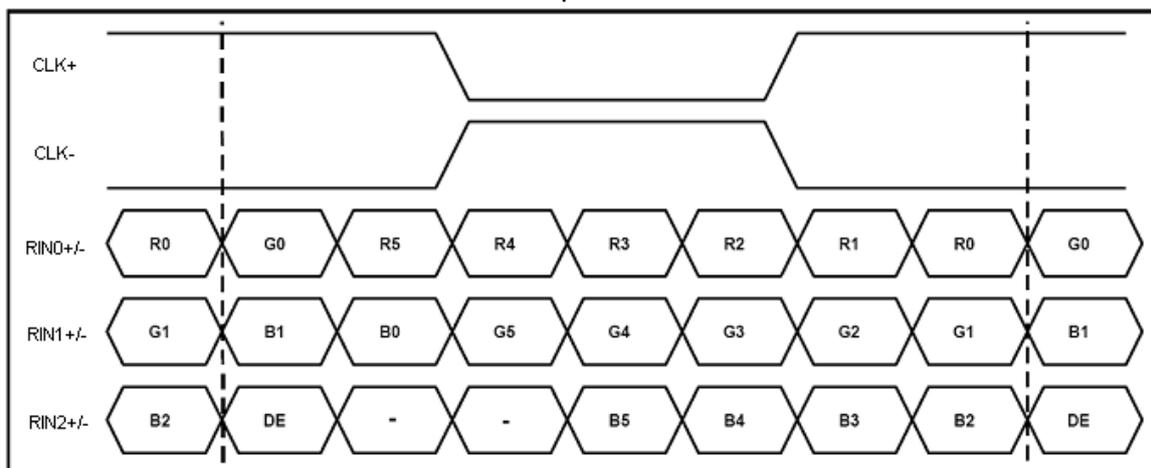


### 6.4 data timing

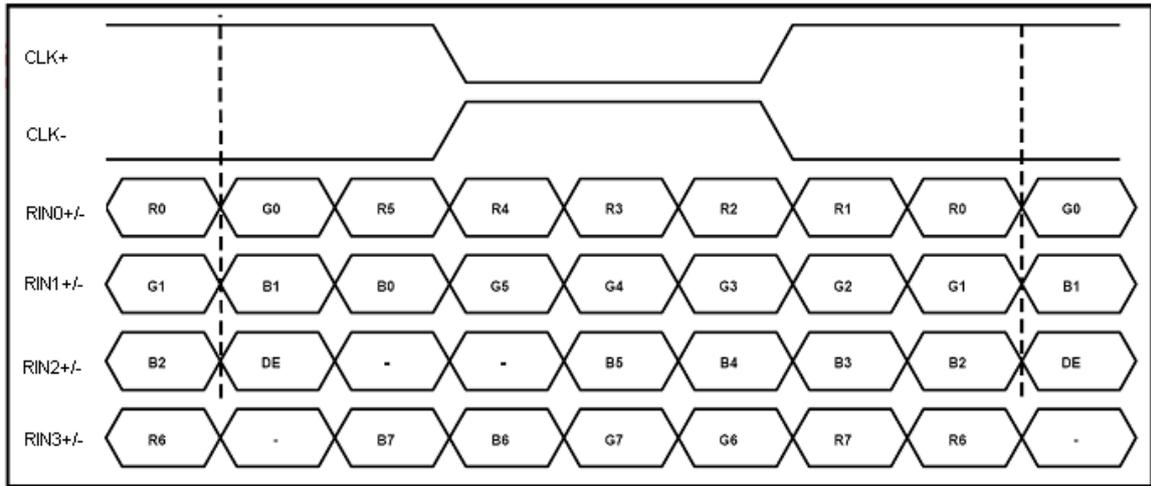
Parameter	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
DCLK frequency	fclk	52	65	71	MHz
Horizontal display area	thd	1024			DCLK
HSD period	th	1114	1344	1400	DCLK
HSD blanking	thb+thfp	90	320	376	DCLK
Vertical display area	tvd	768			$T_H$
VSD period	tv	778	806	845	$T_H$
VSD blanking	tvbp+tvfp	10	38	77	$T_H$

### 6.5 LVDS data input format

SEL68 = "Low" for 6 bits LVDS Input



SEL68 = "High" for 8 bits LVDS Input



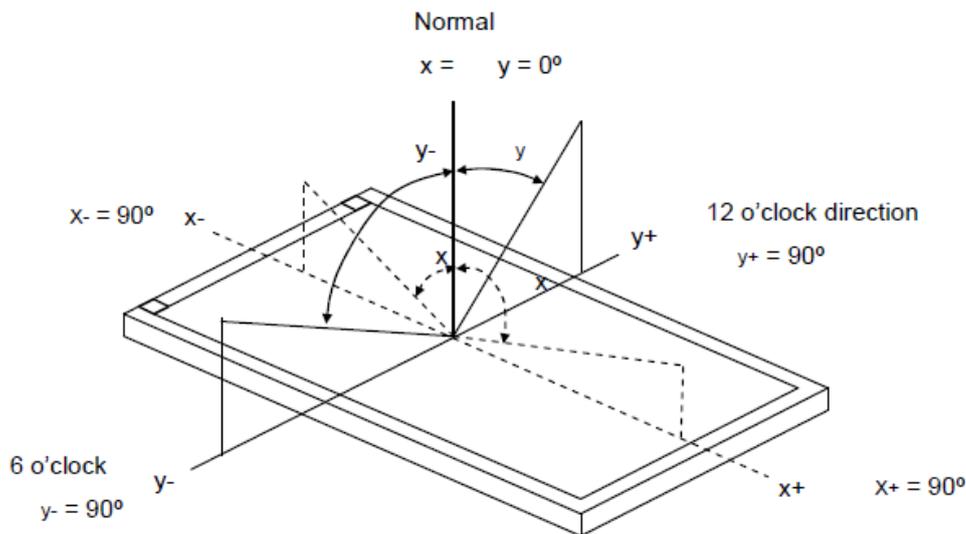
## 7. OPTICAL CHARACTERISTICS

### 7.1 Optical specification

The relative measurement methods of optical characteristics are shown

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Color Chromaticity (CIE 1931)	Wx	$\theta_x=0^\circ, \theta_y=0^\circ$ R=G=B=255	Typ - 0.02	0.305	Typ + 0.02	-	C Light Source (5)
	Wy			0.347			
Center Transmittance	T%	Gray scale	5.06	5.62	-	%	(6),(7),(8)
Contrast Ratio	CR		700	1000	-	-	(2)
Response Time	$T_{R+TF}$	$\theta_x=0^\circ, \theta_y=0^\circ$	-	25	35	ms	(3)
Viewing Angle	Horizontal	x +	CR $\geq$ 10	85	89	-	Deg. (1),(5)
		x -		85	89	-	
	Vertical	y +		85	89	-	
		y -		85	89	-	

Note (1) Definition of Viewing Angle ( $\_x, \_y$ ):



Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

$$\text{Contrast Ratio (CR)} = L_{255} / L_0$$

L255: Luminance of gray level 255

L 0: Luminance of gray level 0

$$CR = CR (5)$$

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (6).

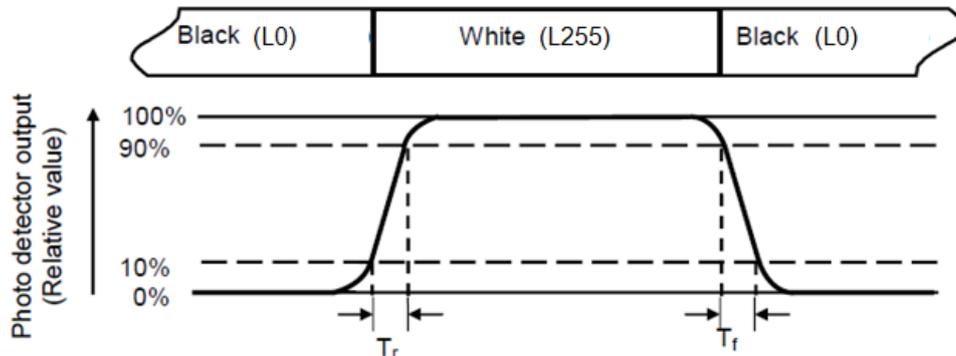
Note (3) Definition of Response Time :

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time ( $T_r$ ) is the time between photo detector output intensity changed from

10% to 90%. And fall time (Tf) is the time between photo detector output intensity changed from 90% to 10%.

RT = RT (5)

RT (X) is corresponding to the Response Time of the point X at Figure in Note (6).



Note (4)

Definition of Luminance of White (Lc):

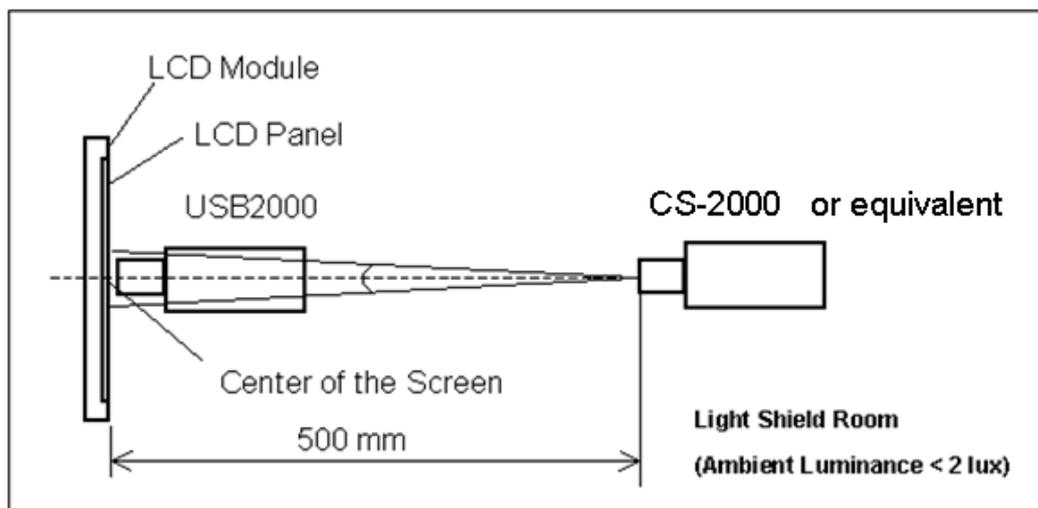
Measure the luminance of gray level 255 at center point

LC = L (5)

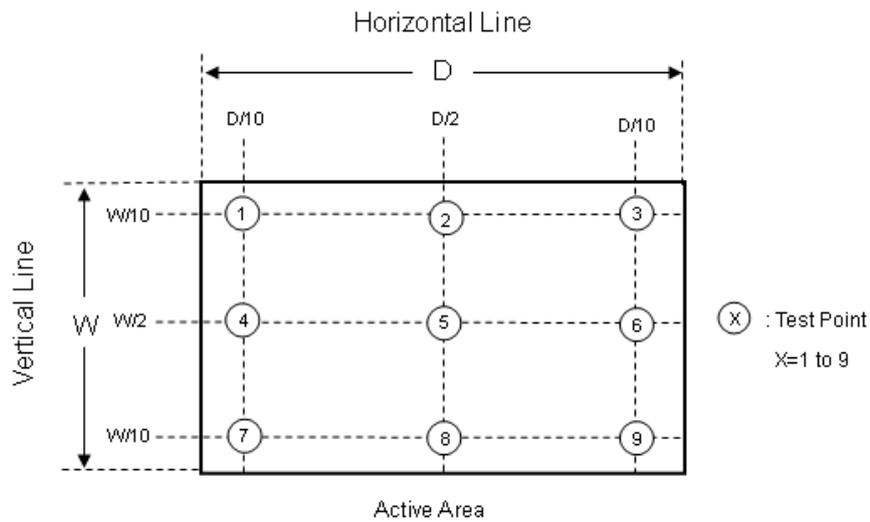
L (x) is corresponding to the luminance of the point X at Figure in Note (6).

Note (5) Measurement Setup:

The LCD module should be stabilized at given temperature for 40 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 40 minutes in a windless room.



Note (6)



Note (7) The listed optical specifications refer to the initial value of manufacture, but the condition of the specifications after long-term operation will not be warranted.

Note (8) Definition of color gamut (C.G%):

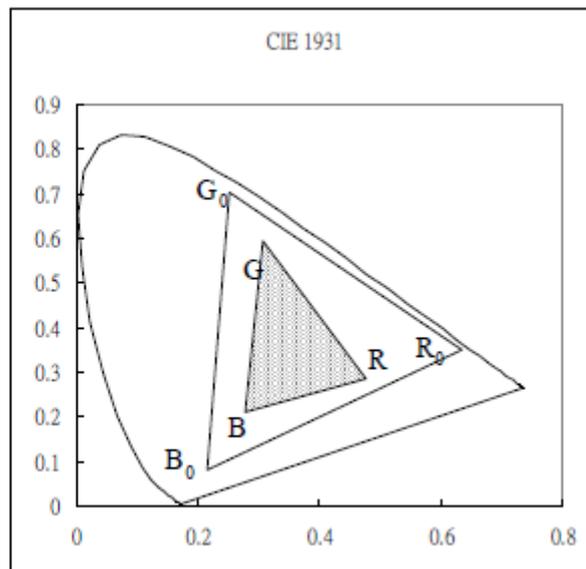
$$C.G\% = \frac{R G B}{R_0 G_0 B_0} * 100\%$$

$R_0, G_0, B_0$  : color coordinates of red, green, and blue defined by NTSC, respectively.

$R, G, B$  : color coordinates of module on 255 gray levels of red, green, and blue, respectively.

$R_0 G_0 B_0$  : area of triangle defined by  $R_0, G_0, B_0$

$R G B$  : area of triangle defined by  $R, G, B$



Note (9) : Polarizer axis degree information

Up polarizer : 0°

Down Polarizer : 90°

## 8. QUALITY ASSURANCE

No.	Test Items	Test Condition	Note
1	High Temperature Storage	85°C, 240hrs	Note 1, 2
2	Low Temperature Storage	-30°C, 240hrs	Note 1, 2
3	High Temperature Operation	85°C, 240hrs	Note 1, 2
4	Low Temperature Operation	-30°C, 240hrs	Note 1, 2
5	High Temperature and High Humidity Storage	60°C, 90%RH, 240hrs	Note 1, 2
6	Thermal Shock	-30°C/0.5h ~ +80°C/0.5h for a total 100 cycles	Note 1, 2
7	Electro Static Discharge	C=150pF,R=330Ω, 5point/panel Air:±4Kv, 5times	Note 2
8	Package Drop Test	Drop in 1 corner,3 edges,6 surfaces, 1 time/direction Height follow ISTA(1A) 0kg ≤ W < 10kg : 76cm, 10kg ≤ W < 19kg : 61cm, 19kg ≤ W < 28kg : 46cm, 28kg ≤ W < 45kg : 31cm, 45kg ≤ W ≤ 68kg : 20cm	Note 2

Note 1: The test samples have recovery time for 2 hours at room temperature before the function check. In the standard conditions, there is no display function NG issue occurred.

Note 2: After the reliability test, the product only guarantees operation, but don't guarantee all of the cosmetic specification.

## 9. PRECAUTIONS

### 9.1 ESD (Electrical Static Discharge) strategy

- [ 1 ] ESD will cause serious damage of the panel, ESD strategy is very important in handling. Following items are the recommended ESD strategy
- [ 2 ] In handling LCD panel, please wear gloves with non-charged material. Using the conduction ring connects wrist to the earth and the conducting shoes to the earth necessary is.
- [ 3 ] The machine and working table for the panel should have ESD protection strategy.
- [ 4 ] In handling the panel, ionized airflow decreases the charge in the environment is necessary.
- [ 5 ] In the process of assemble module, shield case should connect to the ground.

### 9.2 Environment

- [ 1 ] Working environment of the panel should be in the clean room.
- [ 2 ] Because touch panel has protective film on the surface, please remove the protection film slowly with ionized air to prevent the electrostatic discharge.

### 9.3 Assembly and handling precautions

- [ 1 ] Do not apply improper or unbalanced force such as bending or twisting to open cells during assembly.
- [ 2 ] It is recommended to assemble or to install an open cell into a customer's product in clean working areas. The dust and oil may cause electrical short to an open cell or worsen polarizers on an open cell.
- [ 3 ] Do not apply pressure or impulse to an open cell to prevent the damage.
- [ 4 ] Always follow the correct power-on sequence when an open cell is assembled and turned on. This can prevent the damage and latch-up of the CMOS LSI chips.
- [ 5 ] Do not design sharp-pointed structure / parting line / tooling gate on the plastic part of a COF (Chip on film), because the burr will scrape the COF.
- [ 6 ] If COF would be bended in assemble process, do not place IC on the bending corner.
- [ 7 ] The gap between COF IC and any structure of BLU must be bigger than 2 mm. This can prevent the damage of COF IC.
- [ 8 ] The bezel opening must have no burr and be smooth to prevent the surface of an open cell scraped.
- [ 9 ] The bezel of a module or a TV set can not contact with force on the surface of an open cell. It might cause light leakage or scrape.
- [ 10 ] In the case of no FFC or FPC attached with open cells, customers can refer the FFC / FPC drawing and buy them by self.

- [ 11 ] It is important to keep enough clearance between customers' front bezel/backlight and an open cell. Without enough clearance, the unexpected force during module assembly procedure may damage an open cell.
- [ 12 ] Do not plug in or unplug an I/F (interface) connector while an assembled open cell is in operation.
- [ 13 ] Use a soft dry cloth without chemicals for cleaning, because the surface of the polarizer is very soft and easily scratched.
- [ 14 ] Moisture can easily penetrate into an open cell and may cause the damage during operation.
- [ 15 ] When storing open cells as spares for a long time, the following precaution is necessary.
  - [ 15.1 ] Do not leave open cells in high temperature and high humidity for a long time. It is highly recommended to store open cells in the temperature range from 0 to 35°C at normal humidity without condensation.
  - [ 15.2 ] Open cells shall be stored in dark place. Do not store open cells in direct sunlight or fluorescent light environment.
- [ 16 ] When ambient temperature is lower than 10°C, the display quality might be reduced.
- [ 17 ] Unpacking (Cartons/Tray plates) in order to prevent open cells broken:
  - [ 17.1 ] Moving tray plates by one operator may cause tray plates bent which may induce open cells broken. Two operators carry one carton with their two hands. Do not throw cartons/tray plates, avoid any impact on cartons/tray plates, and put down & pile cartons/tray plates gently.
  - [ 17.2 ] A tray plate handled with unbalanced force may cause an open cell damaged. Trays should be completely put on a flat platform.
  - [ 17.3 ] To prevent open cells broken, tray plates should be moved one by one from a plastic bag.
  - [ 17.4 ] Please follow the packing design instruction, such as the maximum number of tray stacking to prevent the deformation of tray plates which may cause open cells broken.
  - [ 17.5 ] To prevent an open cell broken or a COF damaged on a tray, please follow the instructions below:
    - [17.5.1] Do not peel a polarizer protection film of an open cell off on a tray
    - [17.5.2] Do not install FFC or LVDS cables of an open cell on a tray
    - [17.5.3] Do not press the surface of an open cell on a tray.
    - [17.5.4] Do not pull X-board when an open cell placed on a tray.
- [ 18 ] Unpacking (Hard Box) in order to prevent open cells broken:
  - [ 18.1 ] Moving hard boxes by one operator may cause hard boxes fell down and open cells broken by abnormal methods. Two operators carry one hard box with

their two hands. Do handle hard boxes carefully, such as avoiding impact, putting down, and piling up gently.

[ 18.2 ] To prevent hard boxes sliding from carts and falling down, hard boxes should be placed on a surface with resistance.

[ 18.3 ] To prevent an open cell broken or a COF damaged in a hard box, please follow the instructions below:

[18.3.1] Do not peel a polarizer protection film of an open cell off in a hard box.

[18.3.2] Do not install FFC or LVDS cables of an open cell in a hard box.

[18.3.3] Do not press the surface of an open cell in a hard box.

[18.3.4] Do not pull X-board when an open cell placed in a hard box.

[ 19 ] Handling – In order to prevent open cells, COFs , and components damaged:

[ 19.1 ] The forced displacement between open cells and X-board may cause a COF damaged. Use a fixture tool for handling an open cell to avoid X-board vibrating and interfering with other components on a PCBA & a COF.

[ 19.2 ] To prevent open cells and COFs damaged by taking out from hard boxes, using vacuum jigs to take out open cells horizontally is recommended.

[ 19.3 ] Improper installation procedure may cause COFs of an open cell over bent which causes damages. As installing an open cell on a backlight or a test jig, place the bottom side of the open cell first on the backlight or the test jig and make sure no interference before fitting the open cell into the backlight/the test jig.

[ 19.4 ] Handle open cells one by one.

[ 20 ] Avoid any metal or conductive material to contact PCB components, because it could cause electrical damage or defect.

#### **9.4 Lamination precautions**

[ 1 ] Air-Bonding the touch panel or cover is recommended instead of OCA/OCR full lamination.

#### **9.5 Safety precautions**

[ 1 ] If the liquid crystal material leaks from the open cell, it should be kept away from the eyes or mouth. In case of contact with hands, skin or clothes, it has to be washed away thoroughly with soap.

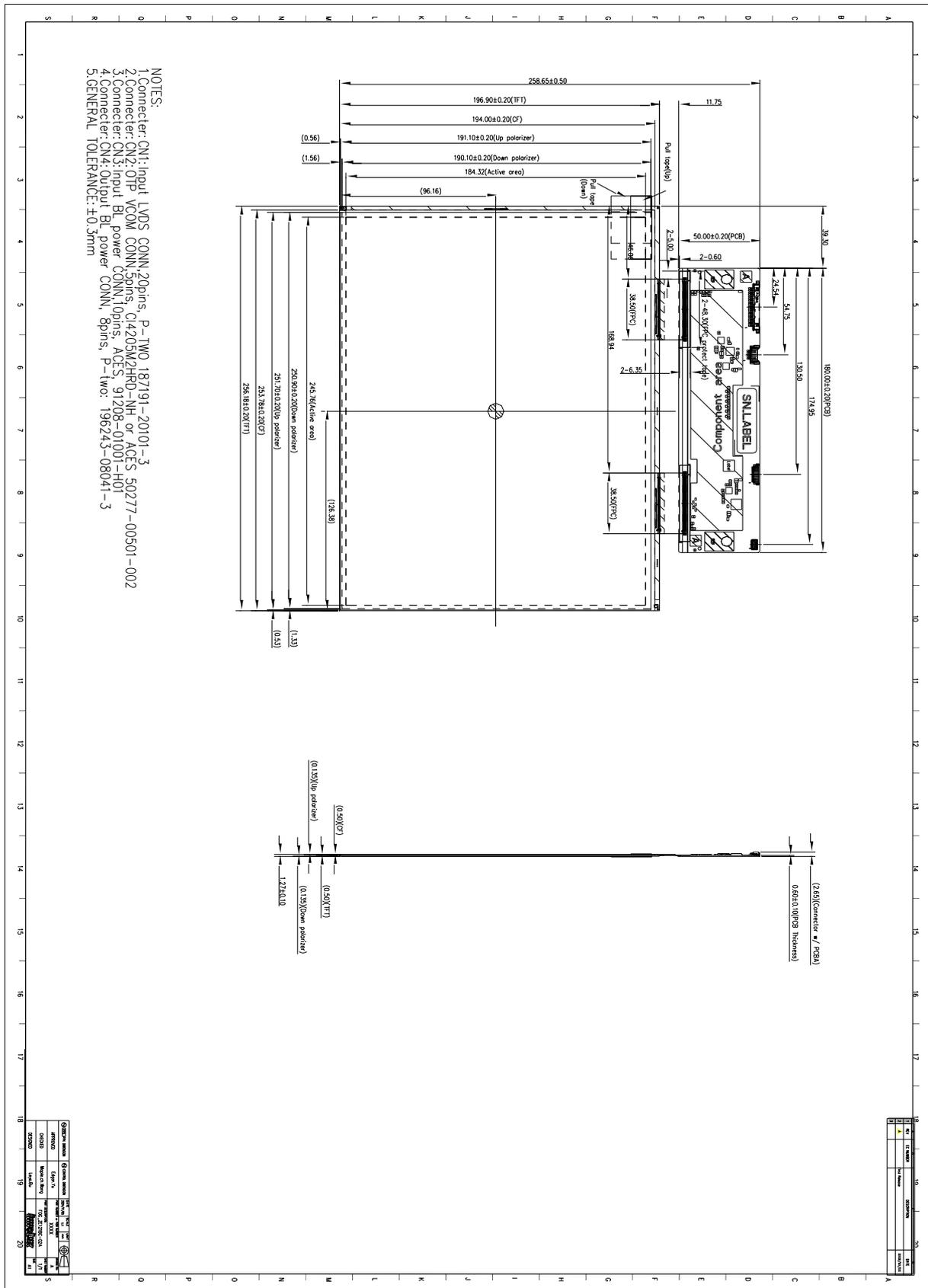
[ 2 ] After the end of life, open cells are not harmful in case of normal operation and storage.

## 9.6 Others

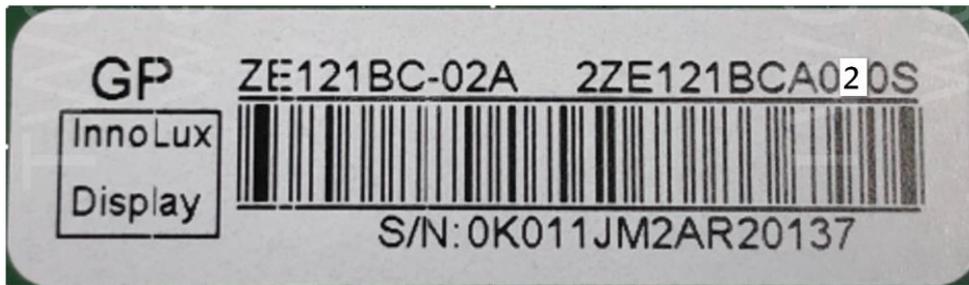
- [ 1 ] Turn off the power supply before connecting and disconnecting signal input cable.
- [ 2 ] Because the connection area of FPC and panel is not so strong, do not handle panel only by FPC or bend FPC.
- [ 3 ] Water drop on the surface or condensation as panel power on will corrode panel electrode.
- [ 4 ] As the packing bag open, watch out the environment of the panel storage. High temperature and high humidity environment is prohibited.
- [ 5 ] In the case the TFT LCD module is broken, please watch out whether liquid crystal leaks out or not. If your hand touches liquid crystal, wash your hands cleanly with water and soap as soon as possible.

## 10. MECHANICAL DRAWING

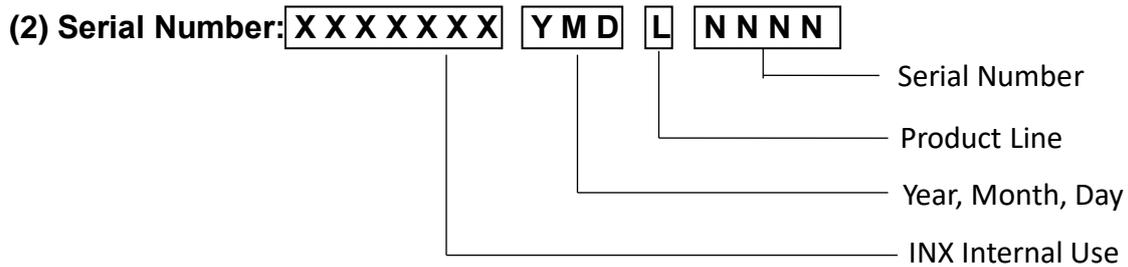
### 10.1 FOG drawing



10.2 FOG label serial label explanation



(1) Model Name: ZE121BC-02A



Serial number included the information as below

(a) Manufactured Date: Year 0~9, 2010~2019

Month 1~9 means Jan. ~Sep.

A~C means Oct.~Dec.

Day 1~9 means 1<sup>st</sup> ~9<sup>th</sup>

A~Z means 10<sup>th</sup>~31<sup>th</sup>

(b) Production Line: 1 means Line1, 2 means Line2...etc

(c) Serial Number: Manufactured sequence of production

## 11. PACKING DRAWING

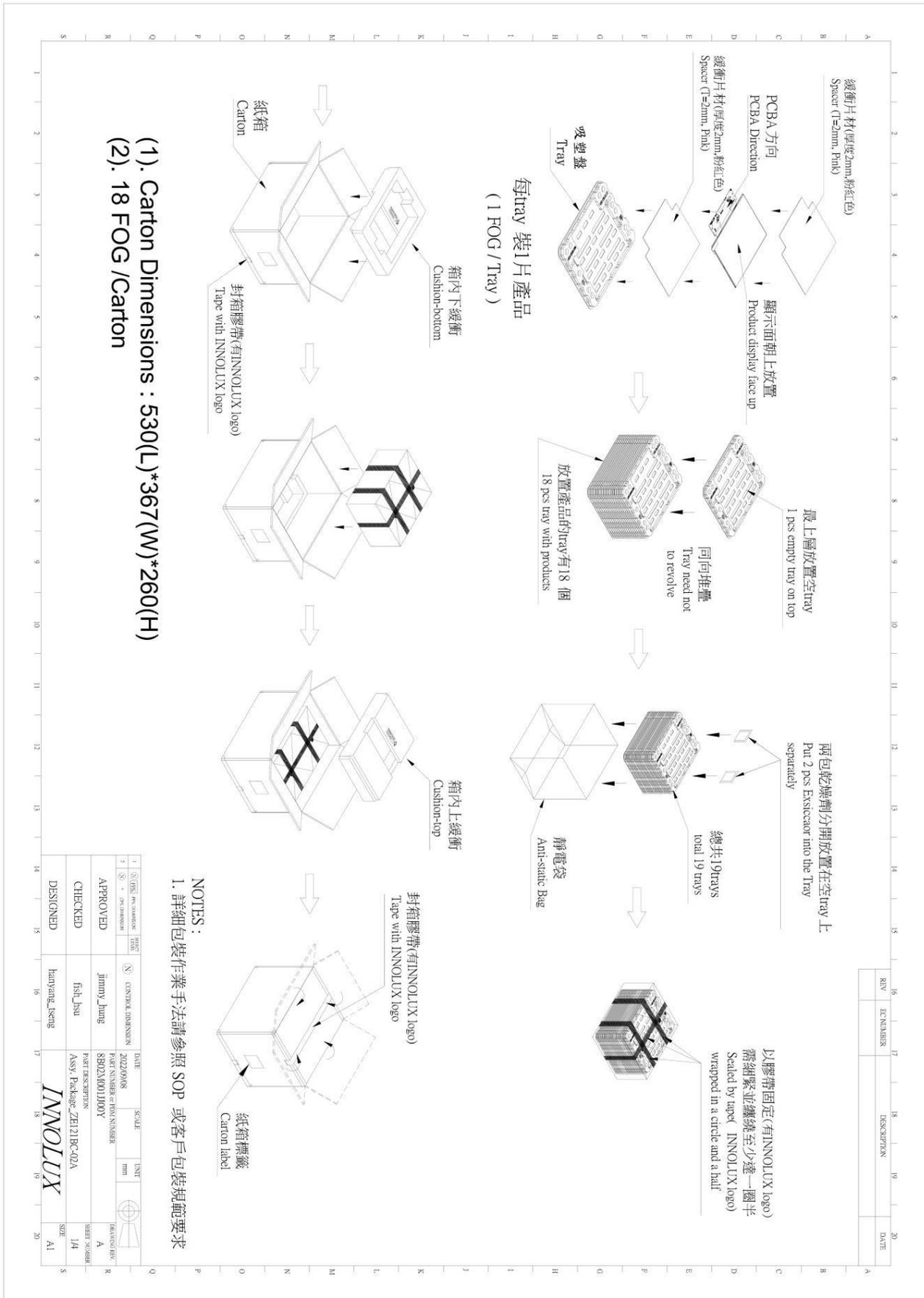
### 11.1 Packaging material table

No	Item	Model (Material)	Dimensions(mm)	Unit Weight (Kg)	Quantity (pcs)	Remark
1	FOG module	ZE121BC-02A	256.18x196.9x1.27	0.15	18	
2	Dust-Proof Bag	LDPE	700 x 530x0.05	0.0595	1	
3	Tray	Tray, PET	359x286x15.4	0.14	19	
4	Spacer	EPE	253x249x2.2	0.0032	36	
5	Cushion	EPE	518x356x115	0.0185	2	
6	Drier	Exsiccator	105 x 80 x 8	0.035	2	
7	Carton	Corrugated paper	530×367×260	0.95	1	
8	Total weight	<b>7kg</b>				

### 11.2 Packaging quantity

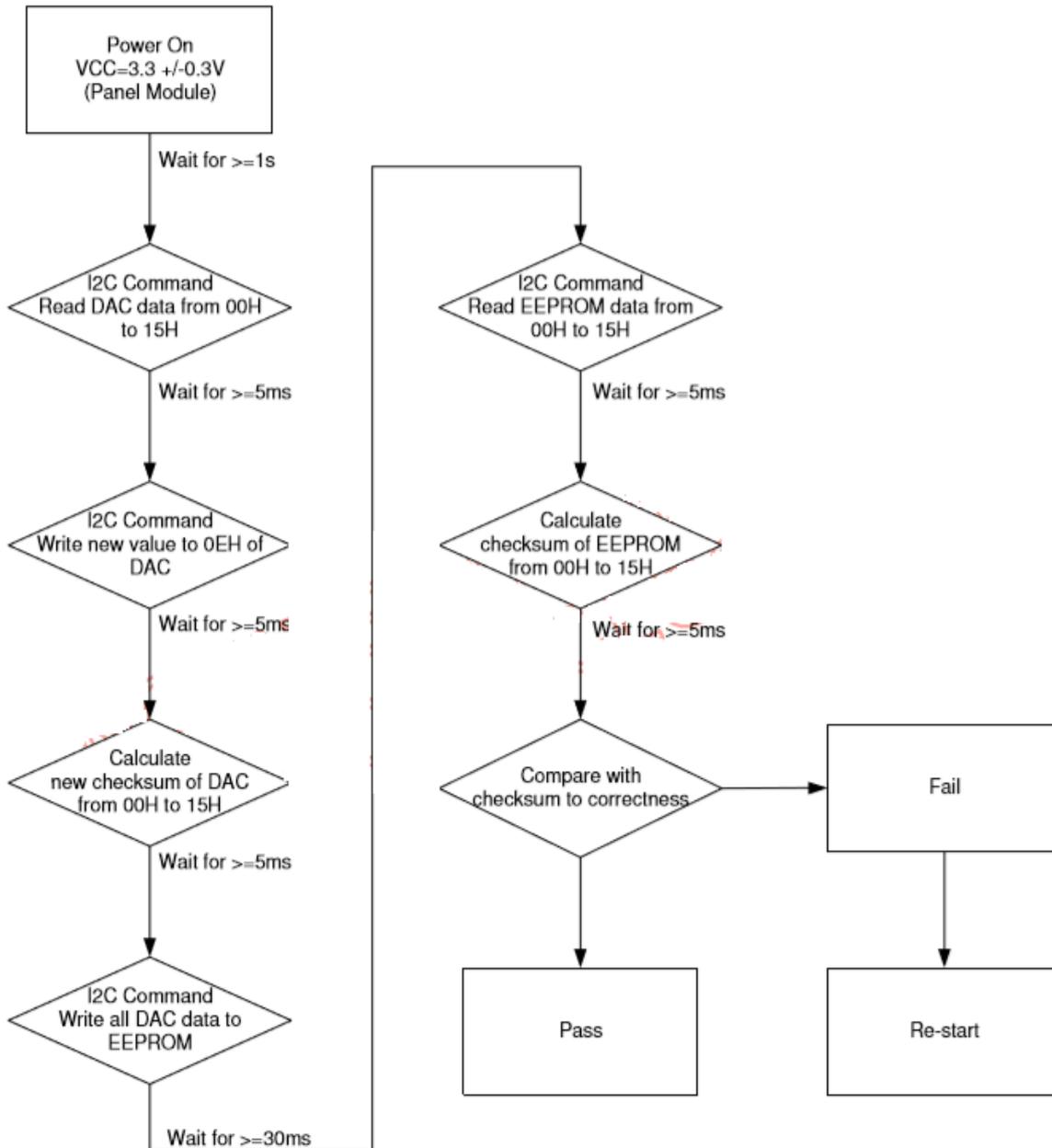
Total Panel quantity of per Carton: 1pcs/ tray x 18 (19-1) tray / Carton = 18 pcs
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## 11.3 Packaging drawing



**Appendix 1**

**1.1 OTP D-VCOM adjust flow**



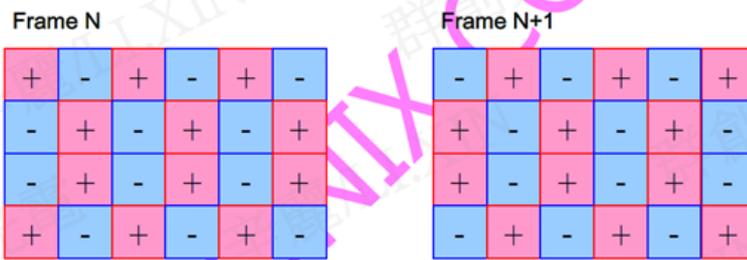
**1.2. OTP D-VCOM I2C register address & setting**

Please refer to IN512-NO03(Novatek) IC datasheet part *I2C Command List and Description* for D-VCOM I2C register address & setting description.

**1.3. Flicker Pattern**

1+2Dot inversion

Single Gate Mode 1+2 dot Inversion (Vertical)



Note: 1. Please wait for 75s while LCM power on at flicker pattern, then adjusting VCOM.  
 2. Please wait for 75s while LCM power on at flicker pattern, then measuring flicker value.

## Appendix 2

CN4 connector applicable FPC & FFC dimension.

